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With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL31C680KBCNBND**
- Description : **CAP, 68pF, 50V, ±10%, C0G, 1206**

A. Samsung Part Number

CL 31 C 680 K B C N B N D
 ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 ± 0.15 mm	W: 1.6 ± 0.15 mm
③ Dielectric	C0G	⑧ Inner electrode	Ni
④ Capacitance	68 pF	Termination	Cu
⑤ Capacitance tolerance	±10 %	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	50 V	⑨ Product	Array(4-element)
⑦ Thickness	0.85 ± 0.15 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type,13"reel(10,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1MHz±10% 0.5~5Vrms
Q	1000 min	
Insulation Resistance	More than 500Mohm·μF	Rated Voltage 60~120 sec.
Appearance	No abnormal exterior appearance	Visual inspection
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
Temperature Characteristics	C0G (From -55°C to 125°C, Capacitance change should be within ±30PPM/°C)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g·F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5%	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating : 80~120°C for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% Tan δ, IR : initial spec.	Solder pot : 270±5°C, 10±1sec.

	Performance	Test condition
Vibration Test	Capacitance change : within $\pm 2.5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours \times 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within $\pm 7.5\%$ Q : 200 min IR : More than $25M\Omega \cdot \mu F$	With rated voltage $40 \pm 2^\circ C$, 90~95%RH, 500 +12/-0 hour
High Temperature Resistance	Capacitance change : within $\pm 3\%$ Q : 350 min IR : More than $50M\Omega \cdot \mu F$	With 200% of the rated voltage Max. operating temperature 1000+48/-0 hour
Temperature Cycling	Capacitance change : within $\pm 2.5\%$ Tan δ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ C$ \rightarrow Max. operating temperature $\rightarrow 25^\circ C$ 5 cycles test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : $260 \pm 0/-5^\circ C$, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.